

ABSTRACT OF THE DISCLOSURE

A method for manufacturing a semiconductor apparatus device includes a plurality of layers on a semiconductor substrate. The method includes the steps of dividing a pattern of at least a layer into a plurality of sub-patterns, and joining the divided sub-patterns to perform patterning. The layer including wiring substantially affects operation of the semiconductor device depending on a positional relationship to any other wiring, the patterning is performed by one-shot exposure using a single mask, and only as to the layer including the wiring substantially affecting the operation of the semiconductor device depending on the positional relationship to any other wiring, the patterning is performed by one-shot exposure, and as to all of the other layers, the patterning is performed by division exposure.